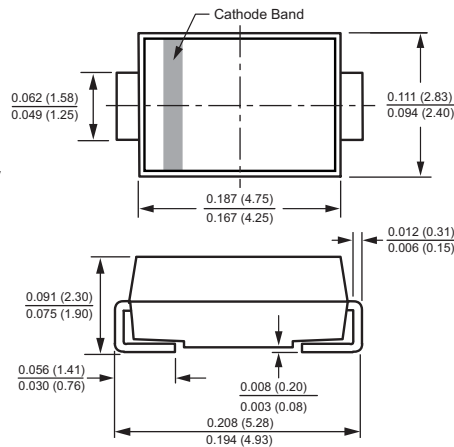


FEATURES

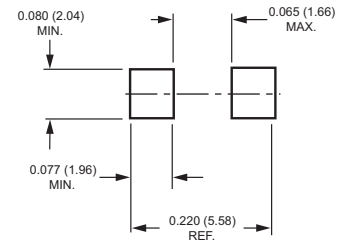
- Glass passivated junction chip
- Voltage range 50~600 volts
- Low profile package
- Built-in strain relief
- Super fast recovery time for high efficiency
- High temperature soldering:
260°C / 10 seconds at terminals

MECHANICAL DATA

- Molded plastic body(UL 94V-0)
- Solder plated terminals
- Polarity: Indicated by cathode band
- Packaging: 12mm tape EIA STD RS-481
- Weight: 0.064gram



Suggested Mounting Pad Layout



SMA (DO-214AC)

Dimensions in inches and (millimeters)

MAXIMUM RATINGS & ELECTRICAL CHARACTERISTICS

Rating at 25°C ambient temperature unless otherwise specified.
Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%

Parameter	Symbol	ES2AA	ES2BA	ES2CA	ES2DA	ES2FA	ES2GA	ES2HA	ES2JA	Unit
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	50	100	150	200	300	400	500	600	V
Maximum RMS Voltage	V _{RMS}	35	70	105	140	210	280	350	420	V
Maximum DC Blocking Voltage	V _{DC}	50	100	150	200	300	400	500	600	V
Maximum Average Forward Rectified Current 60Hz Half-Sine Wave, Resistance Load, T _L = 110°C	I _{F(AV)}	2.0								A
Surge (Non-Repetitive) Forward Current 60Hz Half-Sine Wave, 1 Cycle, T _A = 25°C	I _{FSM}	50								A
Maximum Instantaneous Forward Voltage (Note @ 2.0 A)	V _F	0.95				1.30		1.7		V
Maximum DC Peak @ T _A = 25°C	I _{RRM1}	5.0								μA
Reverse Current @ T _A = 100°C	I _{RRM2}	350								
Maximum Reverse Recovery Time (Note 1)	T _{rr}	35								nS
Typical Thermal Resistance (Note 2)	R _{θJA}	75								°C / W
	R _{θJL}	20								°C / W
Operating Temperature Range	T _J	-55 to +150								°C
Storage Temperature Range	T _{STG}	-55 to +150								°C

Note: 1. Reverse Recovery test conditions: I_F = 0.5A, I_R = 1.0A, I_{RR} = 0.25A
2. P.C.B. Mounted on 0.27 x 0.27" (7.0 x 7.0mm) Copper Pad Area

RATING & CHARACTERISTIC CURVES

FIG.1-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

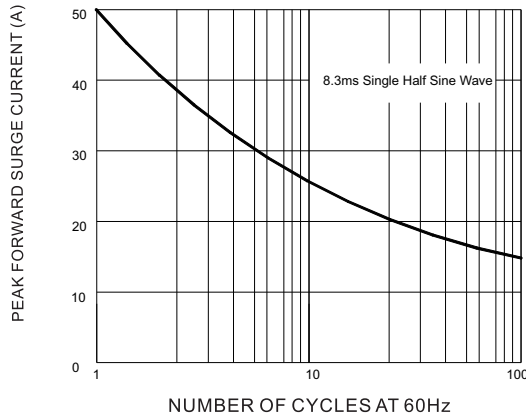


FIG.2-MAXIMUM FORWARD CURRENT DERATING

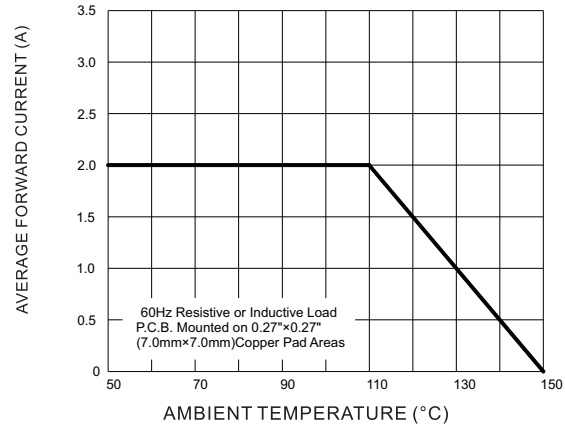


FIG.3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

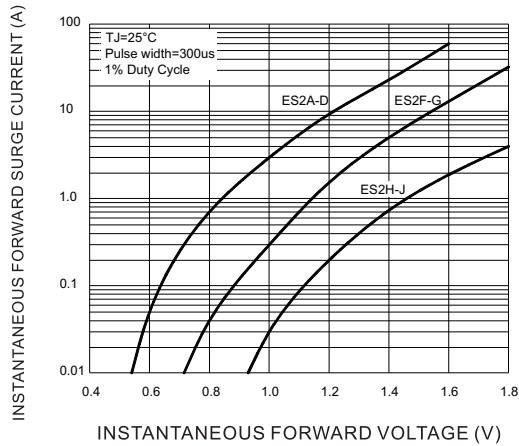


FIG.4-TYPICAL REVERSE CHARACTERISTICS

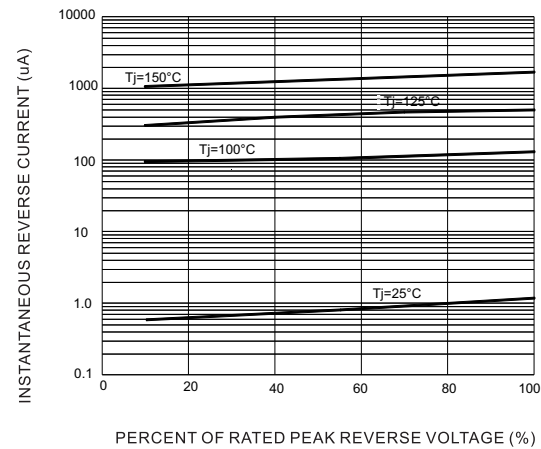
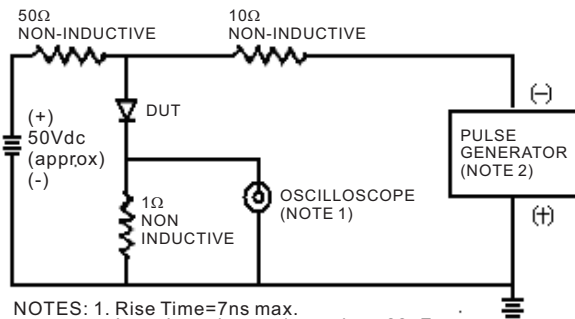


FIG.5-REVERSE RECOVER TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM



- NOTES: 1. Rise Time=7ns max.
Input Impedance=1megohm 22pF
2. Rise Time=10ns max.
Source Impedance=50 ohms.

